

Product Change Notification / ASER-16KRVV582

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27-Jul-2023

Product Category:

Switchtec

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6167 Final Notice: Qualification of E705G as an additional substrate material for selected PM400xx, PM410xx and PM420xx device families available in 753L BBGA (29x29x2.94mm) package assembled at ATK assembly site.

Affected CPNs:

ASER-16KRVV582_Affected_CPN_07272023.pdf ASER-16KRVV582_Affected_CPN_07272023.csv

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of E705G as an additional substrate material for selected PM400xx, PM410xx and PM420xx device families available in 753L BBGA (29x29x2.94mm) package assembled at ATK assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change					
Assembly Site	Amkor Technology Korea (K4), INC (ATK)	Amkor Technology Korea (K4), INC (ATK)	Amkor Technology Korea (K4), INC (ATK)				
Bump Material	Sn1.8Ag	Sn1.8Ag	Sn1.8Ag				
Die Attach Material	SCF-5	SCF-5	SCF-5				
Underfill Material	NAU-27-1F	NAU-27-1F	NAU-27-1F				
Substrate Material	E700GR	E700GR	E705G				

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve productivity by qualifying E705G as an additional substrate material.

Change Implementation Status:In Progress

Estimated First Ship Date: August 27, 2023 (date code: 2335)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2023			>	July 2023				August 2023							
Workweek	9	1	1 1	1 2	1 3		27	28	29	30	31	31	32	33	34	35
Initial PCN Issue Date	Х															
Qual Report Availability										Х						
Final PCN Issue Date										Х						
Estimated Implementation Date																х

Method to Identify Change:Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: February 24, 2023: Issued initial notification.

March 3, 2023: Reissued initial notification with updated qualification plan with revised test temps. July 27, 2023: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on August 27, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_ASER-16KRVV582_Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

PM40028B1-F3EI

PM40036B1-F3EI

PM40052B1-F3EI

PM41028B1-F3EI

PM41036B1-F3EI

PM41052B1-F3EI

PM42028B1-F3EI

PM42036B1-F3EI

PM42052B1-F3EI

Date: Wednesday, July 26, 2023